

Data sheet acquired from Harris Semiconductor SCHS057

CMOS AND Gates

High-Voltage Types (20-Volt Rating)

CD4073B Triple 3-Input AND Gate CD4081B Quad 2-Input AND Gate CD4082B Dual 4-Input AND Gate

CD4073B, CD4081B and CD4082B AND gates provide the system designer with direct implementation of the AND function and supplement the existing family of CMOS gates.

The CD4073B, CD4081B and CD4082B types are supplied in 14-lead dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

CD4073B, CD4081B, CD4082B Types

Features:

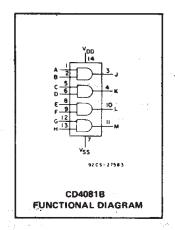
- Medium-Speed Operation -- tp_{LH}, tp_{HL} = 60 ns (typ.) at V_{DD} = 10 V
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) =

1 V at V_{DD} = 5 V

2 V at V_{DD} = 10 V

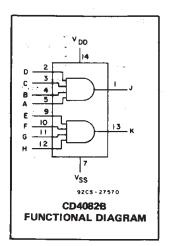
2.5 V at V_{DD} = 15 V

- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE HANGE; (VDD)
Voltages referenced to VSS Terminal)0.5V to +20V
Voltages referenced to VSS Terminal) -0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to VDD +0.5V
DC INPUT CURRENT, ANY ONE INPUT
POWER DISSIPATION PER PACKAGE (PD):
For T _A = −55°C to +100°C to +200°C to +200°
For TA = +1009C to +1289C
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)
OPERATING-TEMPERATURE RANGE (T _A)55°C to +125°C
STORAGE TEMPERATURE RANGE (T _{stg})65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max+265°C



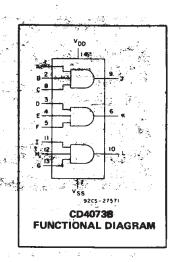
RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHADACTERISTIC	LIM		
CHARACTERISTIC	MIN.	MAX.	UNITS
Supply-Voltage Range (For TA = Full Package Temperature Range)	3	18	٧

DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ =25°C, Input t $_r$,t $_f$ =20 ns, and C $_L$ =50 pF, R $_L$ =200 k Ω

CHARACTE NISTIC	TEST COND	ITIONS	ALL TYPES LIMITS		UNITS
		V _{DD} Volts	TYP.	MAX.	ONTS
Propagation Delay Time,	्र स्टब्स्य (स्टब्स्य)। स्टब्स्य स्टब्स्य	5	125	250	
		10"	60	120	ns
tPHL, tPLH		15	45	90	
Transition Time,		5. 1	100	200	
	- Garage - C. Vice	10	50	100	ns
tthL, ttlH		15	40	80	
Input Capacitance, C _{IN}	Any Input	_	5	7.5	pF



CD4073B, CD4081B, CD4082B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							
	Vo	VIN	VDD	,				+25			UNITS
	(v)	(V)	(V)	56	-40	+85	+125	Min.	Тур.	Max.	1
Quiescent Device Current, IDD Max.	1	0,5	5	0.25	0.25	7.5	7.5	-	0.01	0.25	μА
	- -	0,10	10	0.5	0.5	15	15	-	0.01	0.5	
		0,15	15	- 1.	1	30	30	_	0,01	1	
		0,20	20	5	5	150	150	-	0.02	5	
Output Low (Sink) Current IOL Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1		
	0,5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0,15	15	4.2	4	2.8	2.4	34	6.8	_	
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
(Source) Current, IOH Min.	2.5	0,5	- 5	2	-1.8	-1.3	-1.15	-1.6	-3.2	_	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	_	
Output Voltage:		0,5	5		0	.05			0	0.05	
Low-Level,	·	0,10	10 :		Ö	.05			0	0.05	
VOL Max		0,15	15	0.05			-	0	0.05	v	
Output Voltäge: High-Level, VOH Min.	-	0,5	5		4	.95		4.95	5		ľ
	-	0,10	10		9	.95		9.95	10	-	
	#	0,15	15	14.95 14			14.95	15	-		
Input Low Voltage, VIL Max.	0.5	_	5	·	1	.5	_		_	1.5	
	1	· –	10	1,		3		_	_	3	1
	1.5	_	15	4				_	4		
Input High Voltage, VIH Min.	0.5,4.5	, -	5		3	3.5		3.5	_	_	V
	1,9	_	10	7			7	_			
	1.5,13.5	-	15		1	1		11	_	_	
Input Current Input Max.		0,18	18	±0.1	±0.1	±1	±1	_	±10 ⁻⁵	±0.1	μΑ

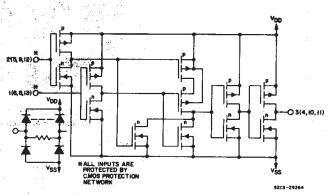


Fig. 1 - Schematic diagram for CD4081B (1 of 4 identical gates).

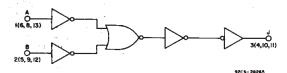


Fig. 2 - Logic diagram for CD4081B (1 of 4 identical gates).

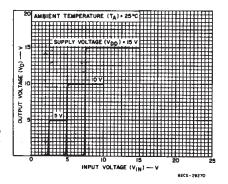


Fig. 3 — Typical voltage transfer characteristics.

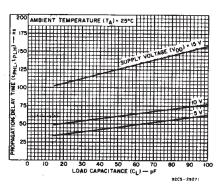


Fig. 4 — Typical propagation delay time as a function of load capacitance.

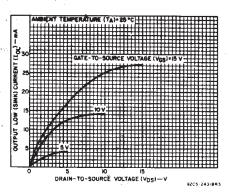


Fig. 5 — Typical output low (sink) current characteristics.

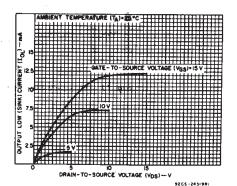


Fig. 6 — Minimum output low (sink) current characteristics.

CD4073B, CD4081B, CD4082B Types

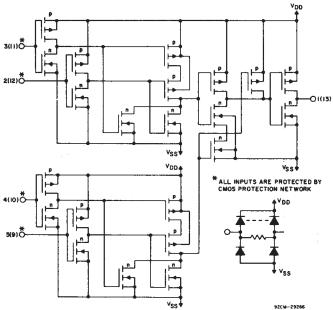


Fig. 7 — Schematic diagram for CD4082B (1 of 2 identical gates).

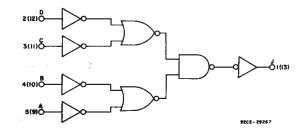


Fig. 9 - Logic diagram for CD40828 (1 of 2 identical gates).

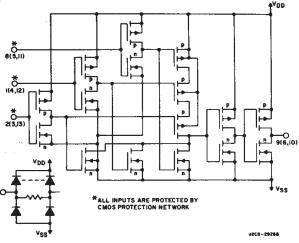


Fig. 11 — Schematic diagram for CD4073B (1 of 3 identical gates).

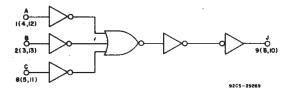


Fig. 13 — Logic diagram for CD4073B (1 of 3 identical gates).

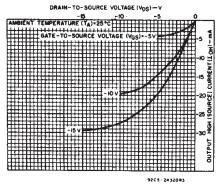


Fig. 8 - Typical output high (source) current characteristics.

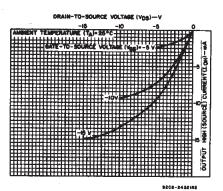


Fig. 10 — Minimum output high (source) current characteristics.

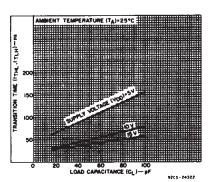


Fig. 12 — Typical transition time as a function of load capacitance

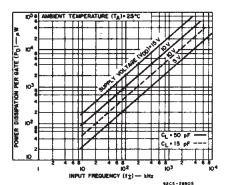


Fig. 14 — Typical dynamic power dissipation per gate as a function of frequency.

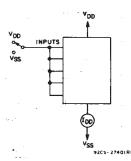


Fig. 15 - Quiescent device current test circuit.

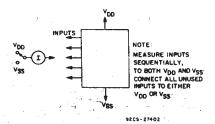


Fig. 16 - Input current test circuit.

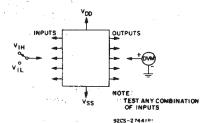
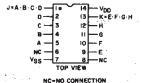


Fig. 17 - Input-voltage test circuit.

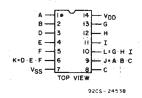
TERMINAL ASSIGNMENTS



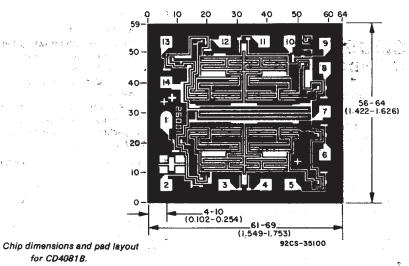
CD4081B

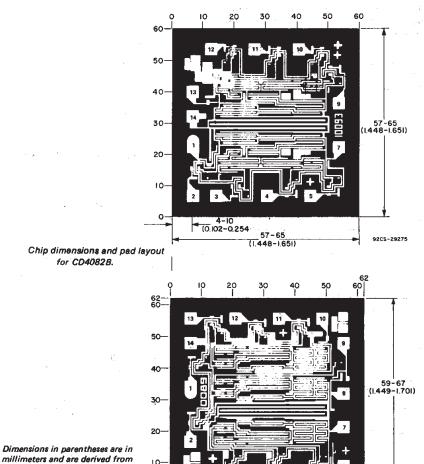


CD4082B



CD4073B





____4-10 (0.102-0.254)

Chip dimensions and pad layout for CD4073B.

the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .

IMPORTANT NOTICE

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